

In the Claims:

Claims 1-26: (cancelled).

Claim 27: (original) A method for manufacturing a semiconductor die package, comprising:

 molding a package base including a plurality of side walls and a floor having a plurality of holes formed therethrough, wherein interior surfaces of the side walls and floor form a cavity sized to hold a semiconductor die and wherein said molding includes molding an electrically conductive frame into the floor, said frame having a plurality of holes formed therein and the holes through the floor register with the holes of said frame; and

 inserting electrically-conductive pins into the holes in the floor such that the pins pass into the holes of the frame and extend from an exterior surface of the floor.

Claim 28: (original) The method of claim 27, further comprising:
 electrically connecting a semiconductor die to the pins and to the frame; and
 attaching a lid to the side walls of the base, the lid and the base sealing the semiconductor die therein.

Claim 29: (original) The method of claim 28, wherein said step of electrically connecting comprises:

 coupling solder balls to the pins and to the frame and coupling the semiconductor die to the solder balls.

Claim 30: (original) The method of claim 28, wherein the step of electrically connecting comprises:

 coupling solder balls to the pins and to the frame;
 placing a substrate over the solder balls;
 placing the semiconductor die on the substrate; and
 electrically connecting the semiconductor die to the substrate.